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de l'accréditation, de la sécurité et qualité
des produits et services

ILNAS-EN 16602-70-16:2021

**Space engineering - Adhesive bonding
for spacecraft and launcher
applications**

Raumfahrtproduktsicherung - Kleben für
Raumfahrzeug- und Trägeranwendungen

Ingénierie spatiale - Collage adhésif pour
les applications d'engins spatiaux et
lanceurs

10/2021



National Foreword

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English version

Space engineering - Adhesive bonding for spacecraft and launcher applications

Assurance produit des projets spatiaux - Utilisations
du collage pour les structure satellites et lanceurs

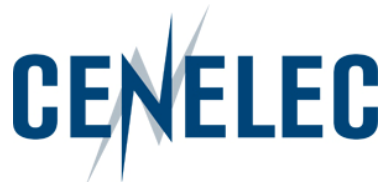
Raumfahrtproduktsicherung - Adhäsionskleben für
Raumfahrt- und Trägeranwendungen

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European Foreword

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This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by April 2022, and conflicting national standards shall be withdrawn at the latest by April 2022.

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